

(0,635 mm) .025"

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material: Liquid Crystal Polymer

Contact Material: Phosphor Bronze

Plating: Au or Sn over 50µ" (1,27 µm) Ni

Operating Temp Range: -55°C to +125°C
Voltage Rating: 275 VAC
Max Cycles: 100

RoHS Compliant: Yes

Processing: Lead-Free Solderable: Yes

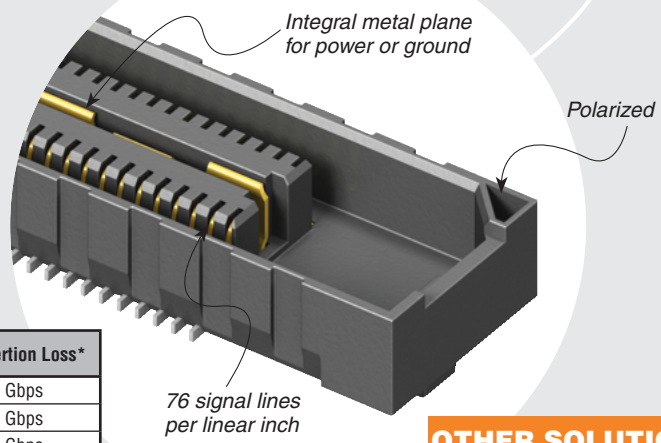
SMT Lead Coplanarity: (0,10 mm) .004" max (019-057)
Board Stacking: For applications requiring more than two connectors per board contact ipg@samtec.com

Board Mates: MIT

Cable Mates: MICD



• Mixed technology footprint



MIT/MIS 5 mm Stack Height	Type	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps

*Performance data includes effects of a non-optimized PCB. Performance data for other stack heights and complete test data available at www.samtec.com?MIS or contact sig@samtec.com

OTHER SOLUTIONS

- Board Spacing Standoffs. See SO Series.

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18,75 mm and 22 mm stack height
- 30µ" (0,76 µm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row
- Edge Mount
- Contact Samtec.



-019, -038, -057
(38 total positions per bank)

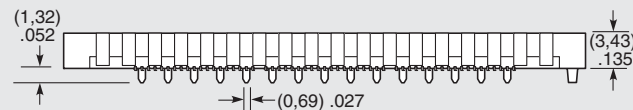
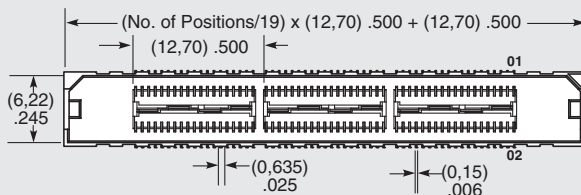
-F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

-L
= 10µ" (0,25 µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, 10µ" (0,25 µm) min Au over 50µ" (1,27 µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

-K
= (7,00 mm) .275" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel



*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press fit) for added retention to PCB.